

B. Amendments to the Claims

Please amend the claims as follows:

1. (Canceled)
2. (Currently amended) A solid state keyboard formed by:
 - (a) depositing a layer of decorative material onto at least a portion of a substrate;
 - (b) depositing a first layer of conductive material as a thin film onto at least a portion of the structure resulting from step (a), said first layer of conductive material being arranged in the form of a first sensing electrode having a shape amenable to substantial coverage by a predetermined object;
 - (c) depositing a second layer of conductive material onto at least a portion of the structure resulting from step (b), at least a portion of said second layer of conductive material being electrically coupled to at least a portion of said first layer of conductive material, said second layer of conductive material being arranged in the form of a first electrical trace and a first bonding pad; and
 - (d) ~~electrically coupling~~ connecting a first electrical component to said first bonding pad.
3. (Previously presented) The solid state keyboard of claim 2, said second layer of conductive material further being arranged in the form of a second sensing electrode having a shape amenable to substantial coverage by a predetermined object.

4. (Currently amended) The solid state keyboard of claim 2 further formed by depositing a first layer of dielectric material onto at least a portion of the structure resulting from step (c), said first layer of dielectric material being arranged in a form that enables ~~electrically coupling~~ connecting said first electrical component to said first bonding pad.

5. (Previously presented) The solid state keyboard of claim 2 wherein said decorative material comprises an organic material.

6. (Previously presented) The solid state keyboard of claim 5 wherein said organic material comprises an epoxy.

7. (Previously presented) The solid state keyboard of claim 5 wherein said organic material is ultraviolet curable.

8. (Previously presented) The solid state keyboard of claim 2 wherein said first layer of conductive material is substantially transparent.

9. (Currently amended) The solid state keyboard of claim 2 wherein said step of ~~electrically coupling~~ connecting comprises soldering.

10. (Previously presented) The solid state keyboard of claim 4, said second layer of conductive material further being arranged in the form of a second bonding pad and said

keyboard further formed by depositing a third layer of conductive material onto at least a portion of said first layer of dielectric material.

11. (Previously presented) The solid state keyboard of claim 10, at least a portion of said third layer of conductive material being electrically coupled to said second bonding pad.

12. (Previously presented) The solid state keyboard of claim 11 further formed by depositing a second layer of dielectric material onto at least a portion of said third layer of conductive material.

13. (Currently amended) A solid state keyboard formed by:

(a) depositing at least one layer of decorative material onto at least a portion of a substrate;

(b) depositing a first conductive material as a thin film onto at least a portion of the structure resulting from step (a), said first conductive material being arranged in the form of a sensing electrode having a shape amenable to substantial coverage by a predetermined object, an electrical trace, and a bonding pad; and

(c) ~~electrically coupling~~ connecting an electrical component to said bonding pad.

14. (Currently amended) The solid state keyboard of claim 13 further formed by depositing a dielectric mask on a portion of the structure resulting from step (b), said mask being

arranged in a form that enables ~~electrically coupling~~ connecting said electrical component to said bonding pad.

15. (Previously presented) The solid state keyboard of claim 13 wherein said decorative material comprises an organic material.

16. (Previously presented) The solid state keyboard of claim 15 wherein said organic material comprises an epoxy.

17. (Currently amended) The solid state keyboard of claim 13 wherein said step of ~~electrically coupling~~ connecting comprises soldering.

18. (Currently amended) A solid state keyboard comprising:

- a substrate;
- at least one layer of decorative material disposed on at least a portion of said substrate;
- a first conductive material disposed as a thin film on at least a portion of said decorative material, said first conductive material arranged in the form of a sensing electrode having a shape amenable to substantial coverage by a predetermined object, an electrical trace and a bonding pad; and
- an electrical component ~~electrically coupled~~ connected to said bonding pad.

19. (Previously presented) The solid state keyboard of claim 18 wherein said decorative material comprises an organic material.

20. (Previously presented) The solid state keyboard of claim 19 wherein said organic material comprises an epoxy.

21. (Previously presented) The solid state keyboard of claim 18 wherein said electrical component is soldered to said bonding pad.

22. (Currently amended) The solid state keyboard of claim 18 further comprising a mask disposed on a portion of said first conductive material, said mask being arranged in a form that enables ~~electrically coupling~~ connecting said electrical component to said bonding pad.

23. (Currently amended) A solid state keyboard comprising:

- a substrate;
- at least one layer of decorative material disposed on at least a portion of said substrate;
- a thin film of a first conductive material disposed on at least a portion of said decorative material, said thin film of a first conductive material being arranged in the form of a first sensing electrode having a shape amenable to substantial coverage by a predetermined object;
- a layer of a second conductive material disposed on at least a portion of said thin film of a first conductive material, said layer of a second conductive material arranged in the

form of a second sensing electrode having a shape amenable to substantial coverage by a predetermined object, an electrical trace, and a bonding pad; and

an electrical component ~~coupled~~ connected to said bonding pad.

24. (Previously presented) The solid state keyboard of claim 23 wherein said decorative material comprises an organic material.

25. (Previously presented) The solid state keyboard of claim 24 wherein said organic material comprises an epoxy.

26. (Previously presented) The solid state keyboard of claim 23 wherein said thin film of a first conductive material is substantially transparent.

27. (Previously presented) The solid state keyboard of claim 23 wherein said electrical component is soldered to said bonding pad.

28. (Currently amended) The solid state keyboard of claim 23 further comprising a mask disposed on at least a portion of said thin film of a first conductive material and at least a portion of said layer of a second conductive material, said mask being arranged in a form that enables ~~electrically coupling~~ connecting said electrical component to said bonding pad.

29. (New) The solid state keyboard of claim 2 wherein said substrate separates said layer of decorative material from said first and second layers of conductive material.

30. (New) The solid state keyboard of claim 2 wherein said substrate does not separate said layer of decorative material from said first and second layers of conductive material.

31. (New) The solid state keyboard of claim 13 wherein said substrate separates said at least one layer of decorative material from said first conductive material.

32. (New) The solid state keyboard of claim 13 wherein said substrate does not separate said at least one layer of decorative material from said first conductive material.

33. (New) A method of making a solid state keyboard comprising the steps of:

- (a) depositing a layer of decorative material onto at least a portion of a substrate, either directly or onto an intervening layer of decorative material;
- (b) depositing a first layer of conductive material as a thin film onto at least a portion of the structure resulting from step (a), said first layer of conductive material being arranged in the form of a first sensing electrode having a shape amenable to substantial coverage by a predetermined object;
- (c) depositing a second layer of conductive material onto at least a portion of the structure resulting from step (b), at least a portion of said second layer of conductive material being electrically coupled to at least a portion of said first layer of conductive material, said second layer of conductive material being arranged in the form of a first electrical trace and a first bonding pad; and
- (d) connecting a first electrical component to said first bonding pad.

34. (New) The method of claim 33 wherein said at least a first layer of decorative material comprises an epoxy.

35. (New) The method of claim 34 wherein said step of connecting comprises soldering.

36. (New) A method of making a solid state keyboard comprising the steps of:

- (a) depositing a layer of decorative material onto at least a portion of a substrate, either directly or onto an intervening layer of decorative material ;
- (b) depositing a first conductive material as a thin film onto at least a portion of the structure resulting from step (a), said first conductive material being arranged in the form of a sensing electrode having a shape amenable to substantial coverage by a predetermined object, an electrical trace, and a bonding pad; and
- (c) connecting an electrical component to said bonding pad.

37. (New) The method of claim 36 wherein said layer of decorative material comprises an epoxy.

38. (New) The method of claim 37 wherein said step of connecting comprises soldering.